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(54) **ORGANIC ELECTROLUMINESCENCE  
PANEL AND METHOD FOR  
MANUFACTURING THE SAME**

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(57) **ABSTRACT**

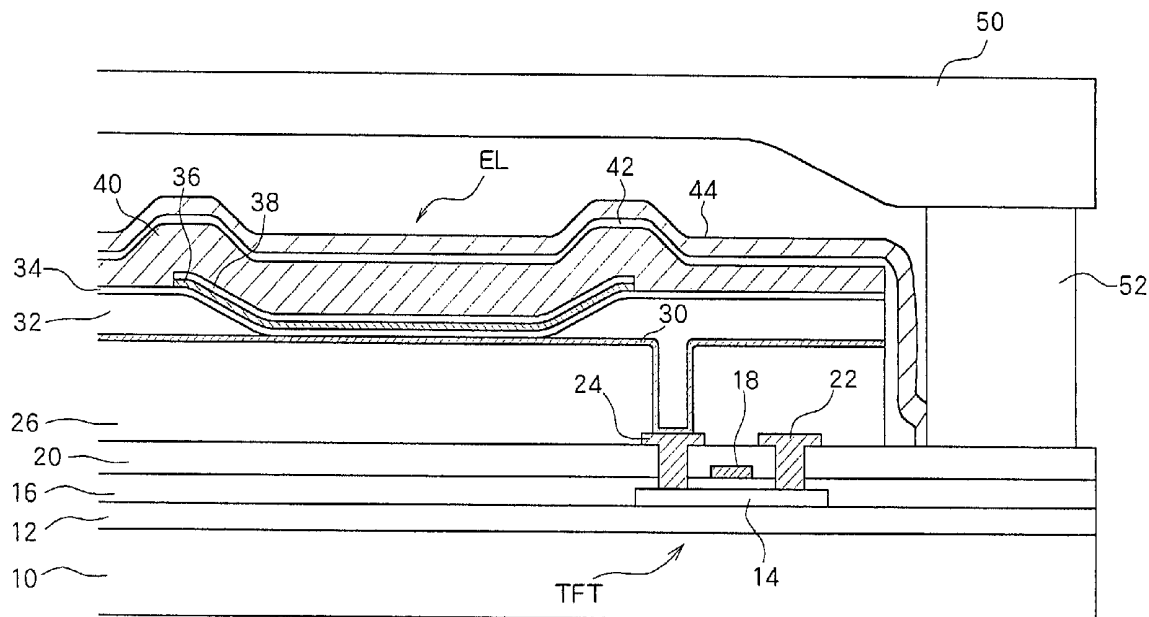
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**Related U.S. Application Data**

(62) Division of application No. 10/463,636, filed on Jun. 16, 2003, now Pat. No. 6,932,666.

On a cathode (40) of an organic EL element, a stress reducing layer (42) formed by a material which is the same as that used for an organic layer of the organic EL element is formed. A moisture block layer (44) formed by a material which is the same as that used for the cathode (40) is then formed on the stress reducing layer (42). Thus, entering of moisture is effectively prevented while the stress is reduced.



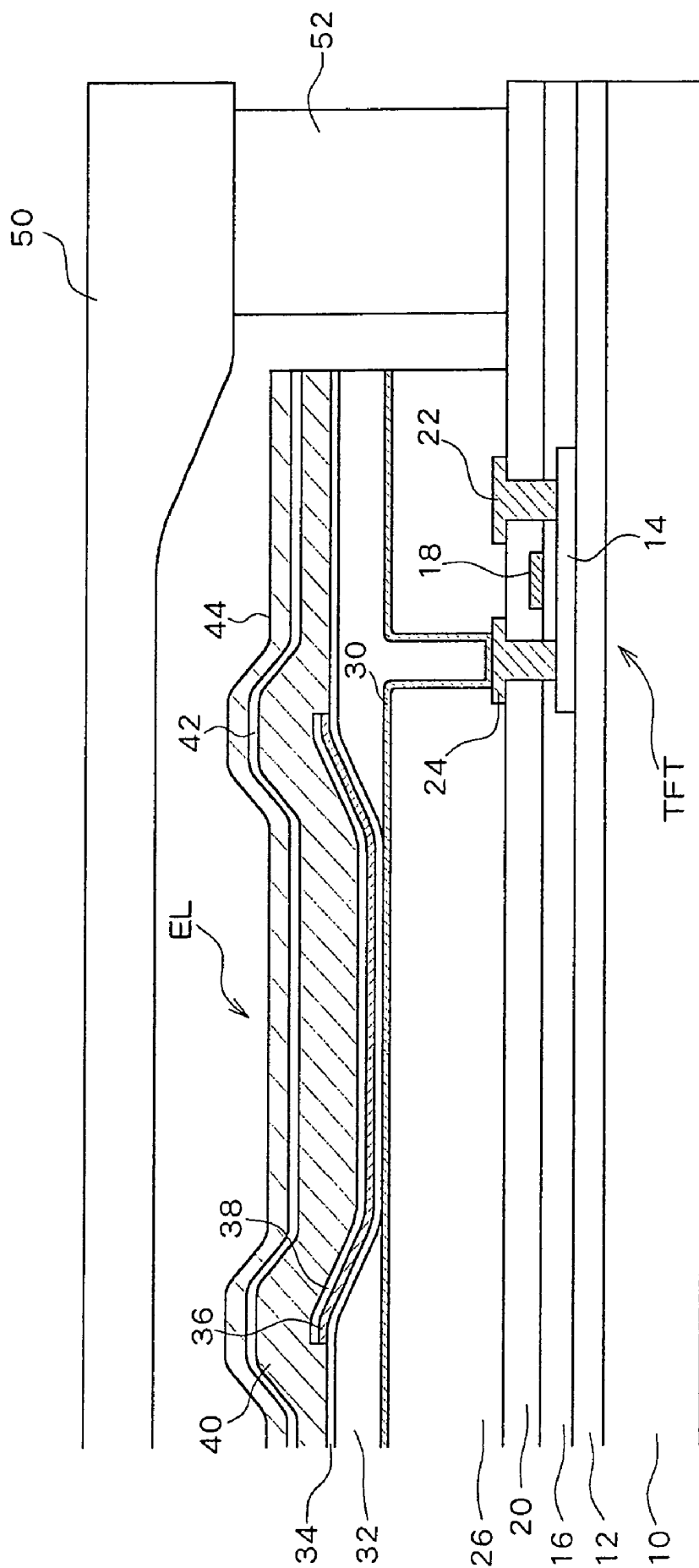


Fig. 1

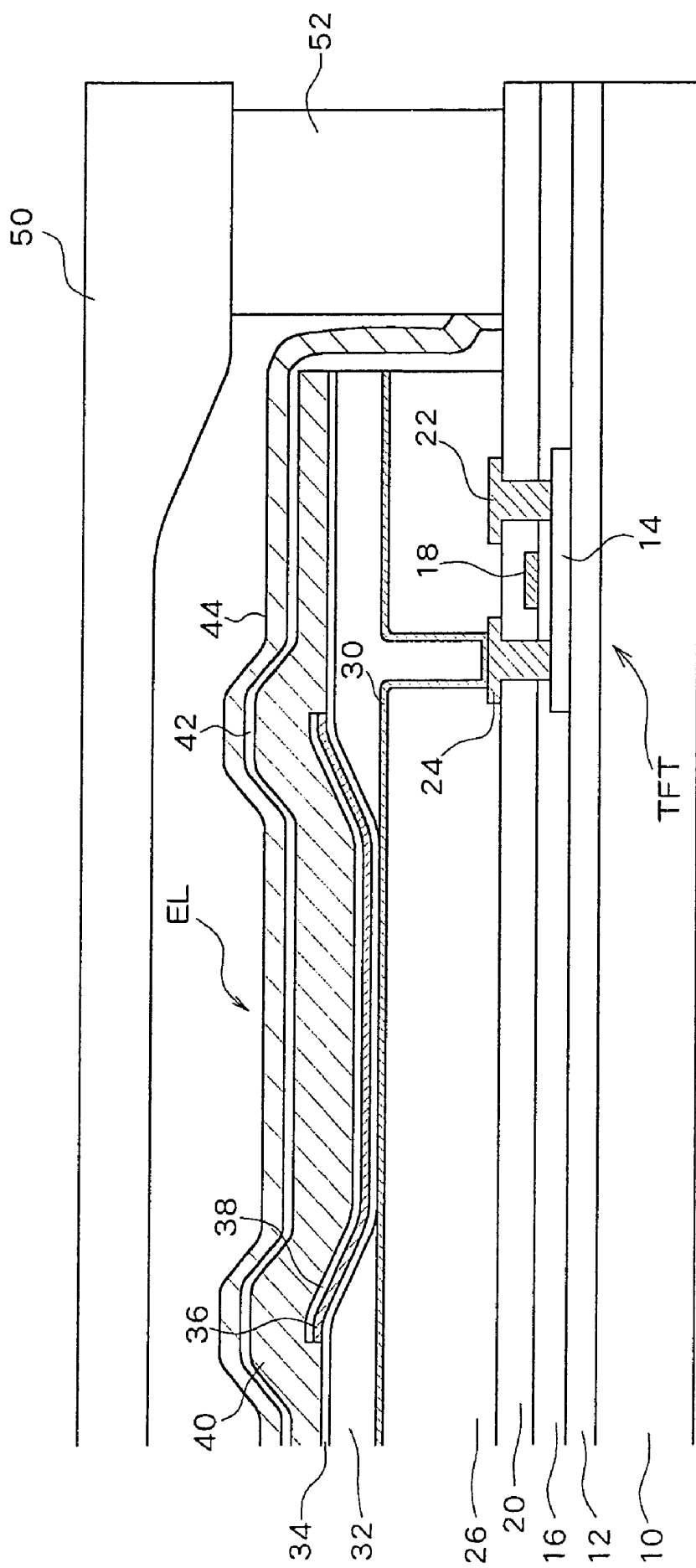


Fig. 2

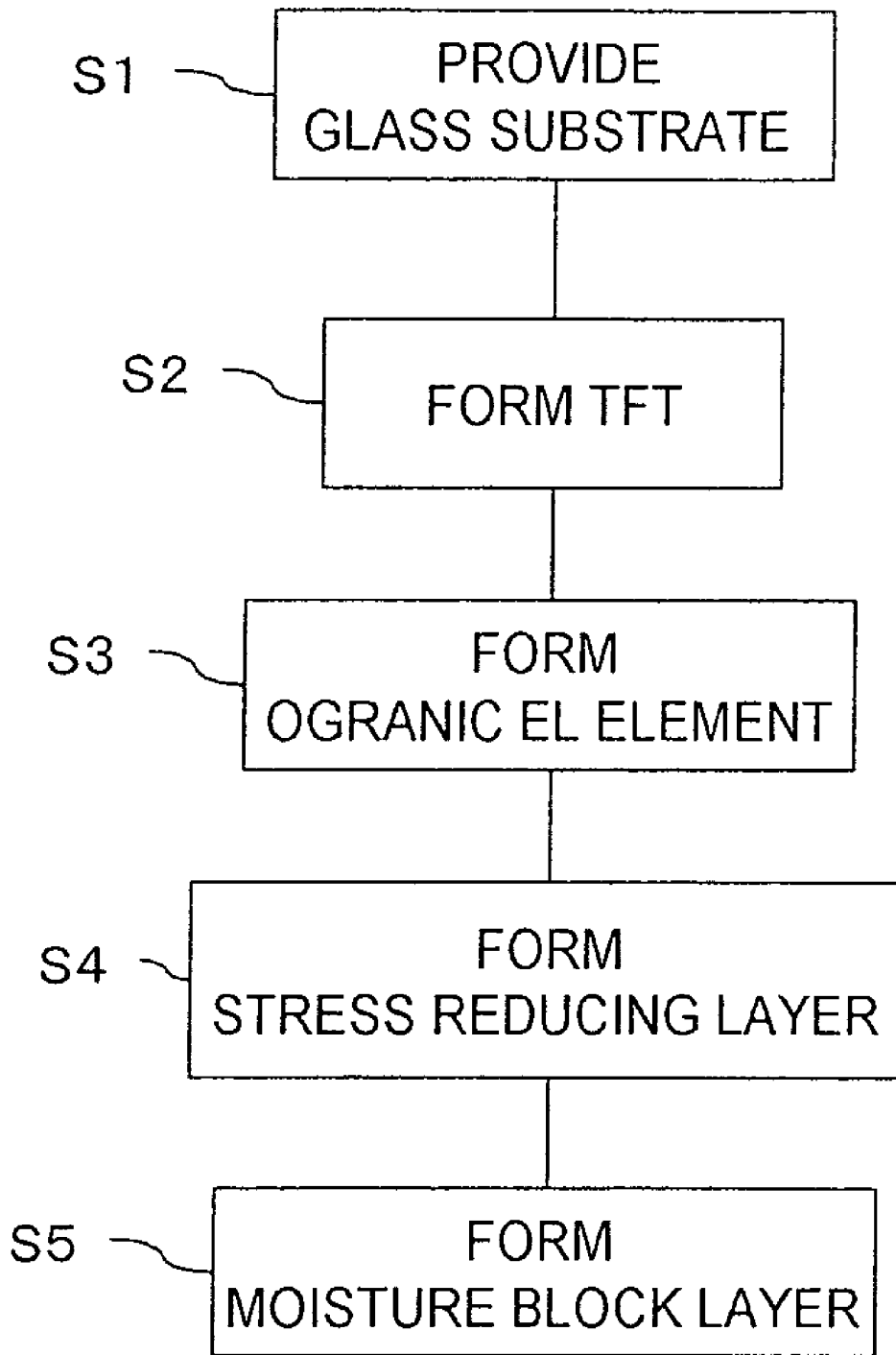


Fig. 3

## ORGANIC ELECTROLUMINESCENCE PANEL AND METHOD FOR MANUFACTURING THE SAME

### BACKGROUND OF THE INVENTION

[0001] 1. Field of the Invention

[0002] The present invention relates to an organic electroluminescence (EL) panel having organic EL elements arranged in a matrix on a substrate, and more particularly to such an organic EL panel which can effectively prevent moisture from entering the organic EL elements.

[0003] 2. Description of Related Art

[0004] Organic EL display panels have conventionally been known as one example of flat display panels. Because, unlike liquid crystal display (LCD) panels, organic EL display panels are self emissive and because organic EL display panels are bright and clear flat display panels, their widespread use is highly expected.

[0005] An organic EL display comprises a great number of organic EL elements arranged in a matrix, and employs these organic EL elements as pixels of a display. Such organic EL displays can be driven passively or actively, similar to LCDs, and, also as is the case with LCDS, active matrix displays are more preferable. More specifically, in active matrix displays, switching elements (typically two elements including a switching element and a driving element) are provided for each pixel and display of each pixel is controlled by controlling the switching elements, whereas in passive driving, a switching element is not provided for each pixel. Of these two types of displays, the active matrix is more preferable because much more precise displays can be achieved.

[0006] The organic EL element emits light when current flows through an organic emissive layer. In many cases, a hole transport layer and an electron transport layer formed of an organic material are provided adjacent to the organic emissive layer so as to assist light emission. These organic layers are apt to degrade when exposed to moisture.

[0007] Accordingly, in organic EL displays, in order to remove moisture from the organic layers, a cathode formed of a metal is provided for covering the upper portion of the organic EL element while a space above the display region (a region where pixels are provided) in which the organic EL element is disposed is made air proof and a drying agent is provided in this space.

[0008] However, there remains a demand for more reliable prevention of diffusion of moisture into the organic layers of the organic EL element. Although it is possible to increase the thickness of the cathode as a solution, for example, when the thickness is too large, the cathode would be deformed and peeled due to the resulting stress.

### SUMMARY OF THE INVENTION

[0009] The present invention advantageously enables reliable prevention of moisture diffusion.

[0010] In accordance with one aspect of the present invention, a moisture block layer is provided on a cathode so that intrusion of moisture into the organic EL element, which is formed under the cathode, can be prevented more reliably.

Further, because the moisture block layer is provided via a stress reducing layer, not directly, on the cathode, the stress of the moisture block layer and of the cathode can be suppressed and deformation of these layers can be reduced.

### BRIEF DESCRIPTION OF THE DRAWINGS

[0011] FIG. 1 is a cross sectional view showing a main portion of a configuration according to an embodiment of the present invention;

[0012] FIG. 2 is a cross sectional view showing a main portion of another configuration according to the embodiment of the present invention; and

[0013] FIG. 3 is a flowchart showing a manufacturing procedure.

### DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENT

[0014] A preferred embodiment of the present invention will be described with reference to the accompanying drawings.

[0015] FIG. 1 is a cross sectional view showing a main portion of one preferred embodiment of the present invention. On a glass substrate **10**, an insulating layer **12** formed of two layers, an SiO<sub>2</sub> layer and an SiN<sub>x</sub> layer, which are accumulated in this order, is provided so as to prevent impurities from entering the glass substrate **10**. On predetermined portions of the insulating layer **12**, a great number of thin film transistors are formed. Although in FIG. 1, a second TFT which is a thin film transistor for controlling current flowing from a power source line to the organic EL element is shown, a first TFT (a switching TFT) is also provided for each pixel for controlling accumulation of voltages supplied from the data line into a capacitor. The second TFT is switched on in accordance with the voltage accumulated in the capacitor for controlling current flowing from the power source line to the organic EL element.

[0016] On the insulating layer **12**, a semiconductor layer **14** which is formed of poly-Si and constitutes an active layer, is formed. Then, a gate insulating film **16** formed of two layers, an SiO<sub>2</sub> layer and an SiN<sub>x</sub> layer, which are accumulated in this order, is formed so as to cover the semiconductor layer **14**. A gate electrode **18** formed of Mo or the like is provided via the gate insulating film **16** above the center portion of the semiconductor layer **14**. An inter-layer insulating film **20** formed of two layers, an SiN<sub>x</sub> layer and an SiO<sub>2</sub> layer, which are accumulated in that order, is further formed so as to cover the semiconductor layer **14**, the gate insulating layer **16**, and the gate electrode **18**. Further, towards ends on the semiconductor layer **14**, a drain electrode **22** and a source electrode **24** made of aluminum, for example, are formed by forming a contact hole through the inter-layer insulating film **20** and the gate insulating film **16**.

[0017] Then, a first planarization film **26** formed of an organic material such as an acrylic resin is formed so as to cover the inter-layer insulating film **20**, the drain electrode **22**, and the source electrode **24**. On the first planarization film **26**, a transparent electrode **30** formed of a material such as ITO is formed so as to serve as an anode of the organic EL element for each pixel.

[0018] A part of the transparent electrode **30** extends down on the source electrode **24**, where the transparent electrode

**30** is formed along the inner surface of a contact hole through which the upper end of the source electrode **24** is exposed. In this manner, the source electrode **24** is directly connected with the transparent electrode **30**.

[0019] Further, portions of the transparent electrode **30** formed in the peripheral region of the pixel area, which corresponds to an area other than the emissive region, are covered with a second planarization film **32** formed of an organic material which is similar to that used for the first planarization film **26**.

[0020] A hole transport layer **34** is then formed over the entire surface of the second planarization film **32** and the transparent electrode **30**. With such a configuration, because the second planarization film **32** has an opening in the emissive region, the hole transport layer **34** is in direct contact with the transparent electrode **30**, which serves as an anode, in the emissive region. On the hole transport layer **34**, an emissive layer **36** and an electron transport layer **38** which are slightly larger than the emissive region are sequentially accumulated in this order for each pixel. On these layers, a cathode **40** made of aluminum or the like is formed. It is preferable that the cathode **40** is formed of lithium fluoride (LiF) and aluminum (Al) which are sequentially formed in this order in a laminate structure.

[0021] Accordingly, when the second TFT is turned on, current is supplied via the source electrode **24** to the transparent electrode **30** of the organic EL element, and flows between the transparent electrode **30** and the cathode **40**. In accordance with the current, the organic EL element emits light.

[0022] According to the present embodiment, a stress reducing layer **42** and a moisture block layer **44** are sequentially formed in this order so as to cover the whole surface of the cathode **40**. The stress reducing layer **42** is formed of an organic material, particularly preferably an organic material which forms the organic EL element. In this embodiment, Alq<sub>3</sub> is used for the stress reducing layer **42**. Alq<sub>3</sub> is a material which emits green light and is used for the emissive layer **36**, and is also used for the hole transport layer **34** for the purpose of utilizing its hole transporting ability. It is also preferable that a material which is the same as that used for the electron transport layer **38** is used for the stress reducing layer **42**. Furthermore, CuPc having electron transporting ability can be used instead of Alq<sub>3</sub>.

[0023] Further, the moisture block layer **44** which is formed on the stress reducing layer **42** is formed of an inorganic material which does not allow transmission of moisture, and is formed, in this embodiment, by a layer having a laminate structure of lithium fluoride and aluminum which is the same as that used in the cathode **40**. Further, silicon nitride (SiN<sub>x</sub>), molybdenum (Mo), or the like may also be used for the moisture block layer **44**. A UV resin, SiO<sub>2</sub>, SiON or the like may further be used.

[0024] As described above, in this embodiment, the moisture block layer **44** is formed on the cathode **40** via the stress reducing layer **42**. It is therefore possible to reliably prevent moisture from diffusing into the organic layers of the organic EL element formed under the cathode **40**. In particular, due to provision of the stress reducing layer **42**, which is formed of an organic material and functions as a layer which reduces stress, a problem that the cathode **40** removes off the organic layers due to the stress, for example, can be prevented.

[0025] Further, by forming the stress reducing layer **42** immediately after formation of the cathode **40**, the stress reducing layer **42** can serve as a protective layer for the cathode **40**. It is therefore possible to reduce adverse effects on the cathode **40** even when the moisture block layer **44** is formed in a separate vacuum chamber by moving the substrate to the chamber, for example.

[0026] While materials for the stress reducing layer **42** and the moisture block layer **44** are not limited to those described above, because the materials described above are also used for forming the organic EL panel of the present embodiment, when these materials are used it is possible to form the stress reducing layer **42** and the moisture block layer **44** using equipments which have been already used in the previous manufacturing steps.

[0027] Normally, a single vacuum chamber is segmented into compartments each used for forming each organic layer of the organic EL element and the cathode **40**, and a substrate is sequentially moved to each compartment for forming each layer by vapor deposition. In such a case, the stress reducing layer **42** and the moisture block layer **44** are formed in the compartments which were already used for forming other layers.

[0028] Typically, a layer of silicon nitride is formed by CVD and a layer of molybdenum is formed by sputtering. Accordingly, when a material used in a step other than the steps for forming the organic EL element is used for the stress reducing layer **42** and the moisture block layer **44**, the operation for forming these layers becomes complicated.

[0029] In the above configuration, the cathode **40**, the stress reducing layer **42**, and the moisture block layer **44** are formed to thicknesses of approximately 400 nm, 150 nm, and 400 nm, respectively. Further, while each of the stress reducing layer **42** and the moisture block layer **44** is formed as a single layer in the above example, these layers may have a multi-layer structure having similar stress reducing layer **42** and moisture block layer **44** accumulated thereon.

[0030] Further, FIG. 1 shows an example configuration in which the end portions of the stress reducing layer **42** and the moisture block layer **44** terminate without hanging down. As shown in FIG. 2, it is preferable to cause the end portions of the stress reducing layer **42** and the moisture block layer **44** to hang down to the surface of the first planarization film **26**, thereby covering the side ends of the organic layers or the like.

[0031] While FIG. 1, which is a cross sectional view showing a main portion, shows only one pixel having one organic EL element, a plurality of pixels having the above configuration are actually disposed in a matrix. In a peripheral portion of the display region where these pixels are disposed in a matrix, a horizontal driving circuit and a vertical driving circuit for driving each pixel, as well as other connecting lines are formed. To a TFT substrate on which these circuits are formed, a sealing substrate is connected only in the peripheral region so as to make the substrates air-proof, thereby forming an EL panel.

[0032] An organic EL panel is formed according to the procedure shown in FIG. 2, for example. First, a glass substrate **10** is provided (S1), and a great number of TFTs are formed on the glass substrate (S2). Then, an anode **30**, organic layers including a hole transport layer **34**, an emis-

sive layer **36**, and an electron transport layer **38**, and a cathode **40** are formed to form an organic EL element (S3).

[0033] After the organic EL element is formed as described above, a stress reducing layer **42** is formed (S4). In the present embodiment, the stress reducing layer **42** is formed by a material which is the same as that used in either the hole transport layer **34**, the emissive layer **36**, or the electron transport layer **38**. Accordingly, as a vacuum chamber for forming the stress reducing layer **42**, the vacuum chamber which was used for forming the organic layers of the organic EL element can be used.

[0034] Then, a moisture block layer **44** is formed on the stress reducing layer **42** (S5). In the present embodiment, the moisture block layer **44** is formed by a material which is the same as that used for the cathode **40**. Accordingly, as a vacuum chamber for forming the moisture block layer **44**, the vacuum chamber which was used for forming the cathode **40** can be used.

[0035] While the preferred embodiment of the present invention has been described using specific terms, such description is for illustrative purposes only, and it is to be understood that changes and variations may be made without departing from the spirit or scope of the appended claims.

1. An organic EL panel having a plurality of organic EL elements arranged in a matrix on a substrate, in which

each organic EL element includes an anode, a cathode, and an organic emissive layer disposed between the anode and the cathode, and

the cathode is formed as a common electrode for the plurality of organic EL elements arranged in a matrix,

the organic EL panel comprising:

a moisture block layer which is provided on the common cathode for preventing moisture from entering the layers formed under the cathode, and

a stress reducing layer which is provided between the cathode and the moisture block layer.

2. An organic EL panel according to claim 1, wherein

the cathode and the moisture block layer are formed of the same material.

3. An organic EL panel according to claim 1, wherein

the stress reducing layer is formed of an organic material.

4. An organic EL panel according to claim 3, wherein

the stress reducing layer is formed of a material which is used for forming an organic layer constituting the organic EL element.

5. An organic EL panel according to claim 4, wherein the stress reducing layer is formed of an organic material including Alq<sub>3</sub> or CuPc.

6-7. (canceled)

8. An organic EL panel according to claim 1, wherein the stress reducing layer covers side ends of the organic emissive layer.

9. An organic EL panel according to claim 1, wherein the moisture block covers side ends of the organic emissive layer.

10. An organic EL panel according to claim 1, wherein the stress reducing layer covers side ends of the organic emissive layer.

\* \* \* \* \*

专利名称(译)	有机电致发光面板及其制造方法		
公开(公告)号	<a href="#">US20050269949A1</a>	公开(公告)日	2005-12-08
申请号	US11/177710	申请日	2005-07-08
[标]申请(专利权)人(译)	西川隆司 池田德宏		
申请(专利权)人(译)	西川隆司 池田德宏		
当前申请(专利权)人(译)	SANYO ELECTRIC CO. , LTD.		
[标]发明人	NISHIKAWA RYUJI IKEDA NORIHIRO		
发明人	NISHIKAWA, RYUJI IKEDA, NORIHIRO		
IPC分类号	H05B33/04 H01L27/32 H01L51/50 H01L51/52 H05B33/10 H05B33/26 H05B33/00		
CPC分类号	H01L51/5237 H01L27/3244 H01L51/5253 H01L51/524		
优先权	2003165459 2003-06-10 JP 2002176358 2002-06-17 JP		
其他公开文献	US7135817		
外部链接	<a href="#">Espacenet</a> <a href="#">USPTO</a>		

摘要(译)

在有机EL元件的阴极(40)上,形成由与用于有机EL元件的有机层的材料相同的材料形成的应力降低层(42)。然后,在应力降低层(42)上形成由与用于阴极(40)的材料相同的材料形成的防潮层(44)。因此,在减小应力的同时有效地防止了水分的进入。

